

REV.	ECN NO.	CONTENT	DATE	ENGINEER
AO			2023 20/04	

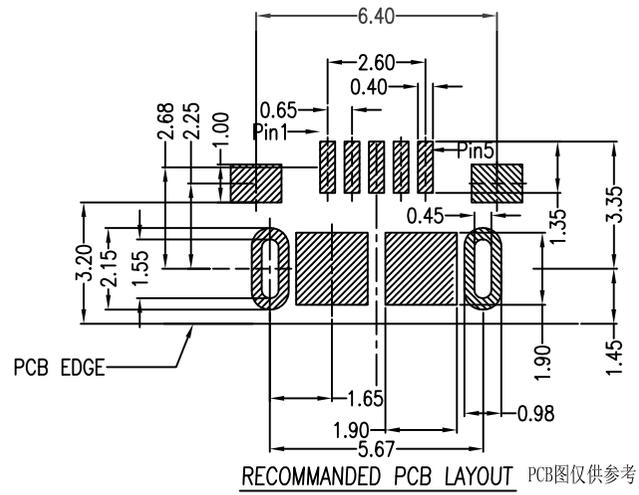
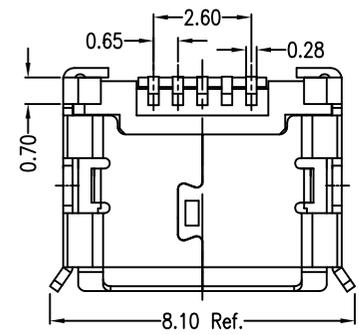
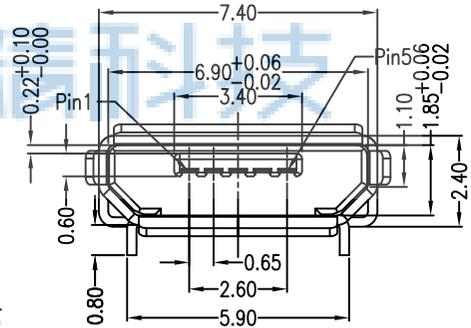
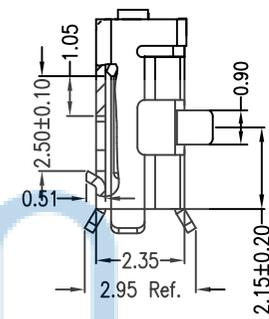
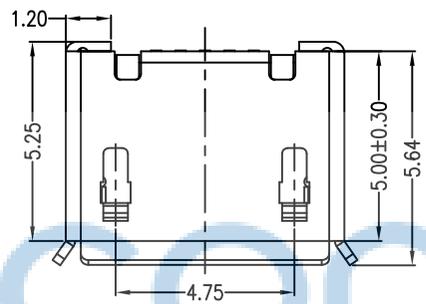
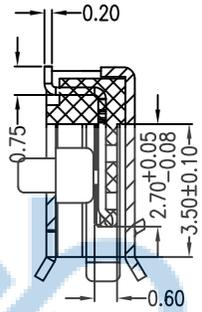
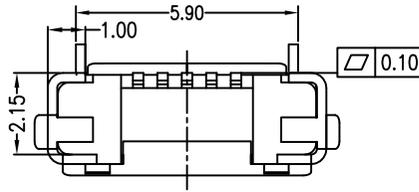
Note:

1.Material:

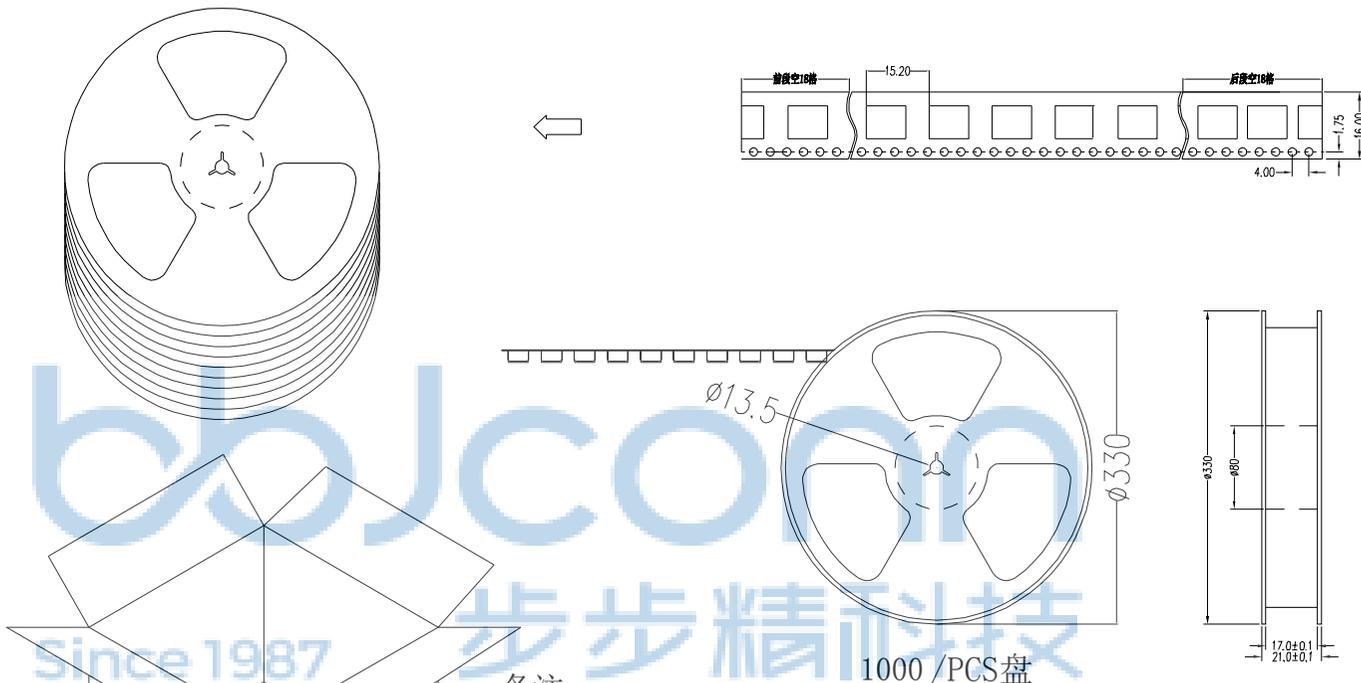
- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm contact area Au flash plating;
- 1.3 Shell:copper or SUS304,t=0.25mm Sn planting 60U" min.

2.Specification:

- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30°C~80°C
- 2.8 Solderability: 90% area min;



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APPD.	JM_Zheng	23/05/02	PJ. NO.: MC.01.21-21-1003		
CHKD.	LYX	23/05/02	SIZE: A4 DRW NO.:		
PDWG.NO:	0113-1	DR.	SGF	23/05/02	FINISH: SEE NOTES    MAT'L.: SEE NOTES SCALE: N/A    REV.: A3    UNIT: mm    PAGE: 1/1



备注:

1. 包装数量: 1000 /PCS/ 盘, 10盘/箱或15盘/箱。
2. 包装袋长度: 每盘前后各空10-20个空格, 中间包装。
3. 材质:  
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$   
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$   
卷盘: 聚苯乙烯。

纸箱规格: 345\*345\*23MM

纸箱规格: 345\*345\*35MM



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